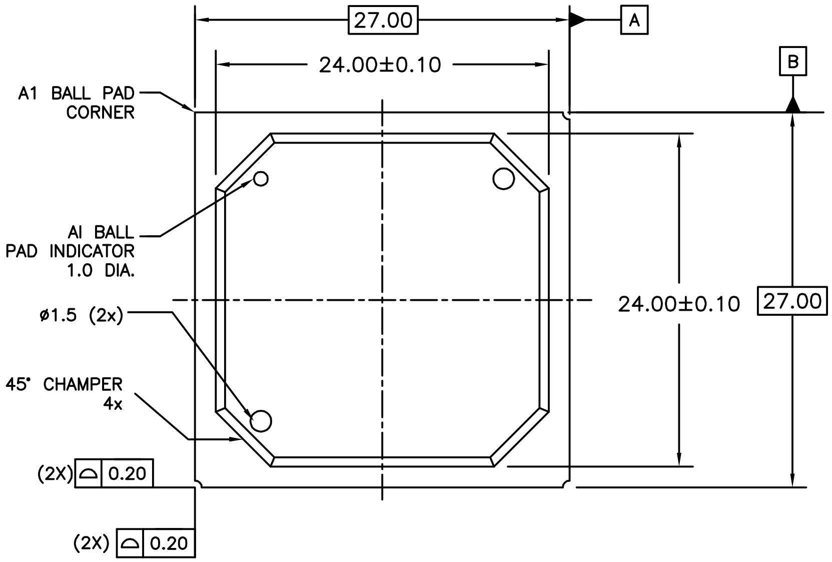
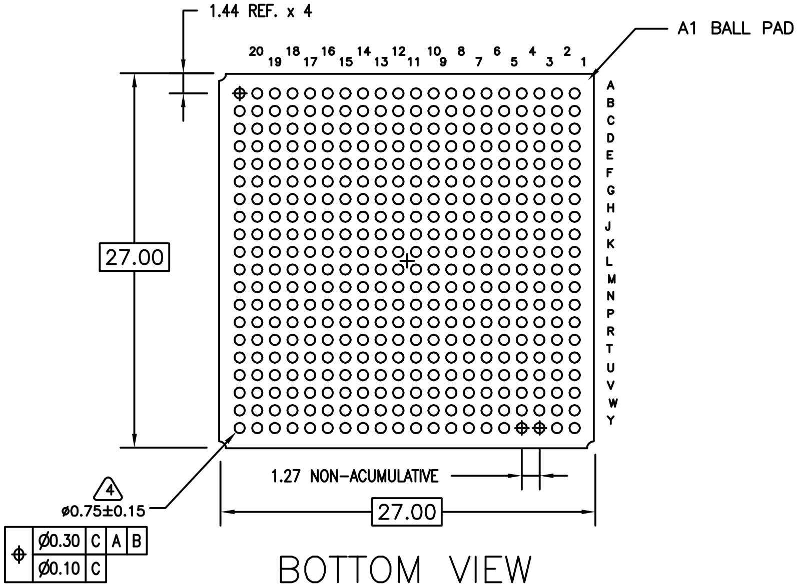
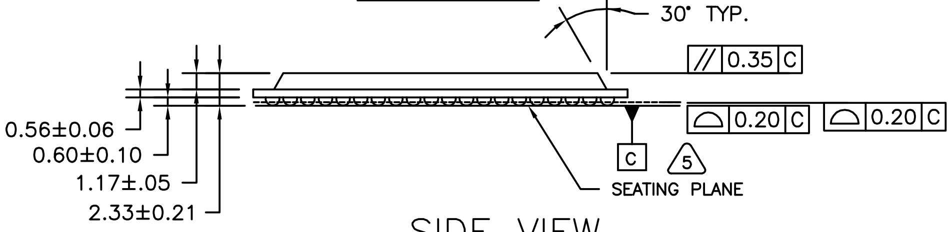


TOP VIEW



BOTTOM VIEW



SIDE VIEW

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS UNLESS OTHERWISE SPECIFIED.
2. ALL DIMENSIONS AND TOLERANCE CONFORM TO ASME Y 14.5M–'94
3. MATERIAL MUST COMPLY WITH BANNED AND RESTRICTED SUBSTANCES SPEC # 10–0131.
4. △ DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO PRIMARY DATUM C
5. △ PRIMARY DATUM C AND SEATING PLANES ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. BALL MATRIX CONFORMS TO JEDEC MS034 VARIATION BAL–2.
7. ALL DIMENSIONS APPLY TO LEADED (–), LEAD FREE (+) PKG. CODES.
8. PACKAGE CODE: V400T–2

–DRAWING NOT TO SCALE–

MAXIM

TITLE:
PACKAGE OUTLINE, 400 BALLS PBGA, THERMALLY ENHACED
27.0x27.0x2.33mm, 1.27mm PITCH, 4 LAYER

APPROVAL	DOCUMENT CONTROL NO.	REV.	
	21–0306	B	1/1